

Technoprobe S.p.A. Company Presentation

September 2023





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Company overview

Reference Market

Business Model

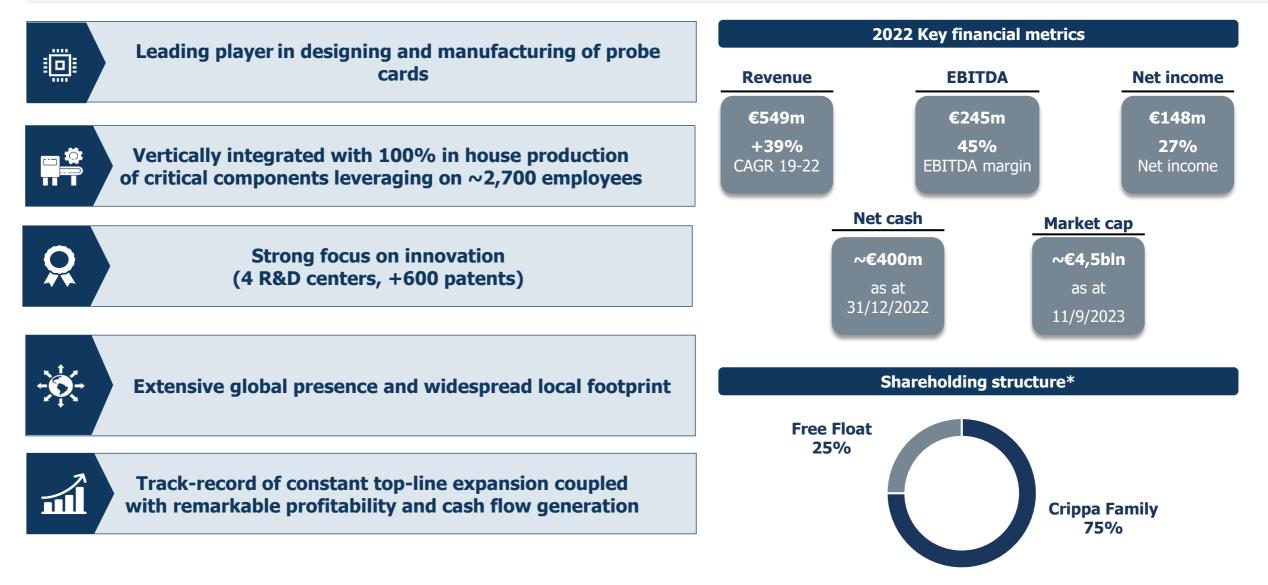
Key Financial data



Company Overview







INNOVATION BEGINS WITH US

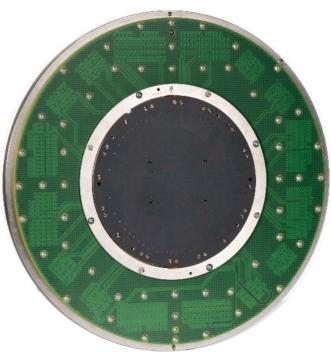


What does Technoprobe do?



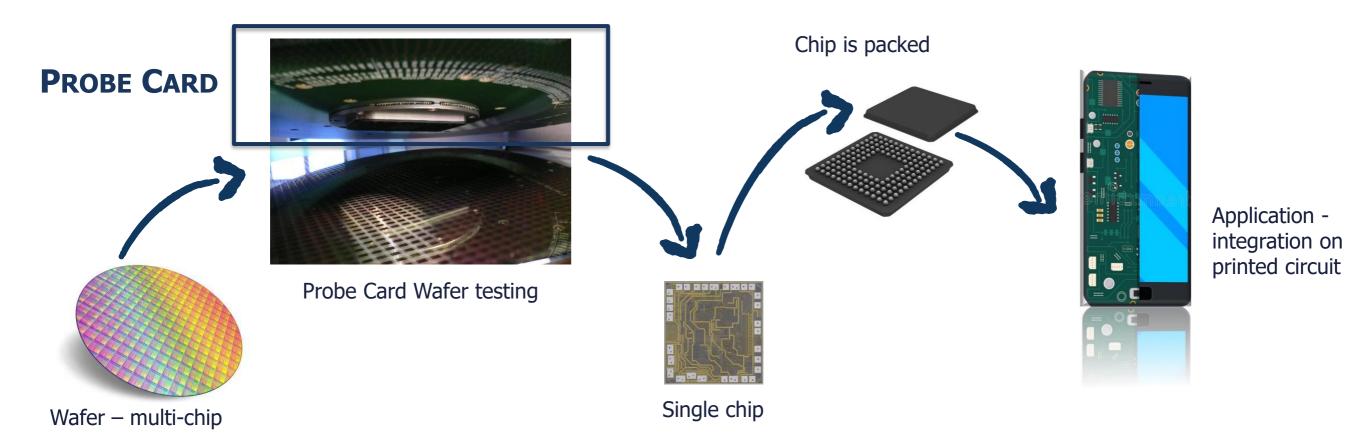


is specialized in the design, development and manufacture of Probe Cards for chips testing



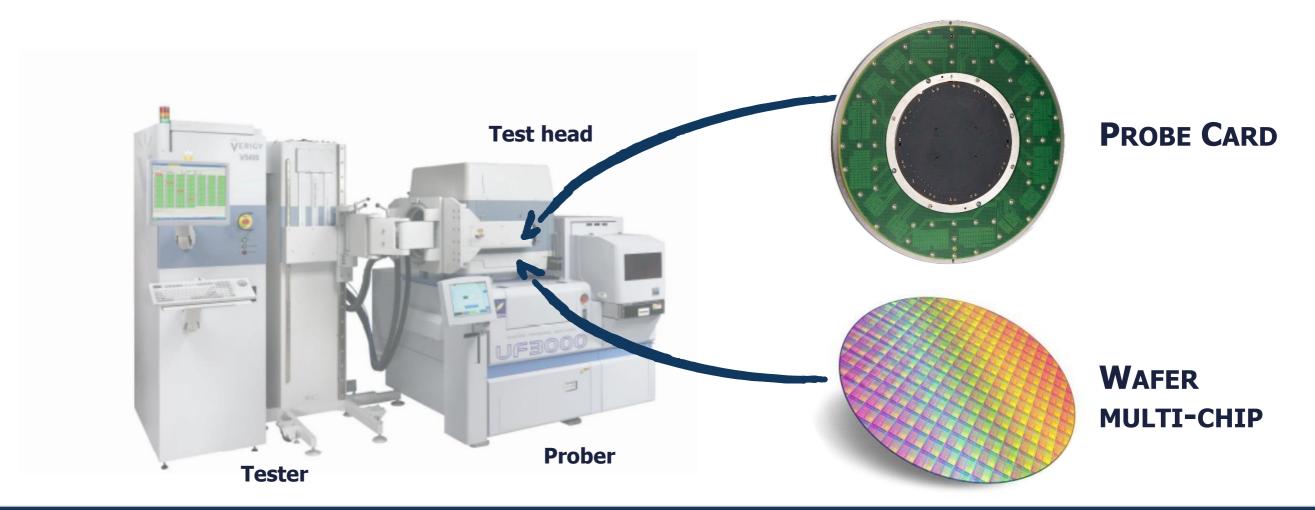


A Probe Card is an **electromechanical interface** that allows a chip to be tested when it is **still on the wafer**





The probe card has very thin needles (**probes**) that touch the terminals (pads) of chips, thus electrically connecting to a **tester**







INNOVATION BEGINS WITH US

Source: company annual reports; rounded figures Note: data are not fully comparable due to different accounting methodologies (2000-2018 ITA GAAP and 2019-2020 IFRS) and changes in consolidation perimeter

Our leadership team



Chairman (Executive), shareholder



17 years in Technoprobe Vice Chairman (Executive), shareholder









Stefano Beretta 1 year in Technoprobe CFO

INNOVATION BEGINS WITH US

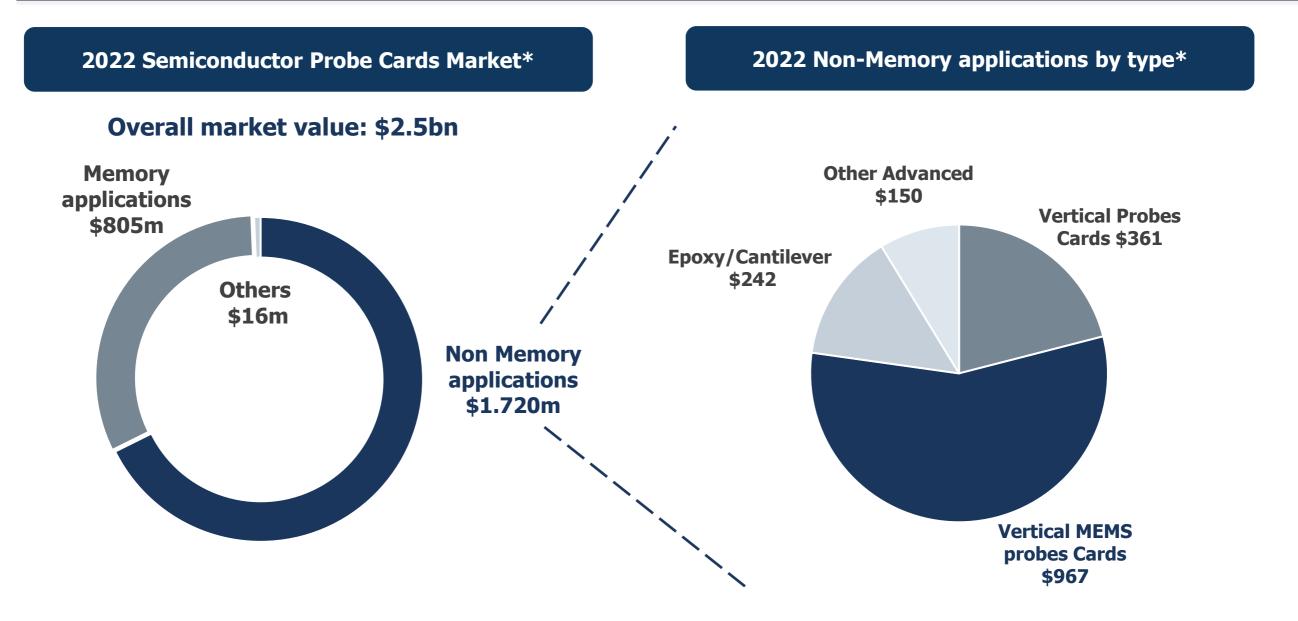


Reference Market





Overview of the Semiconductor Probe Cards market



*Source: TechInsights Market Report 2023, update April 23 Rounded figures, \$m



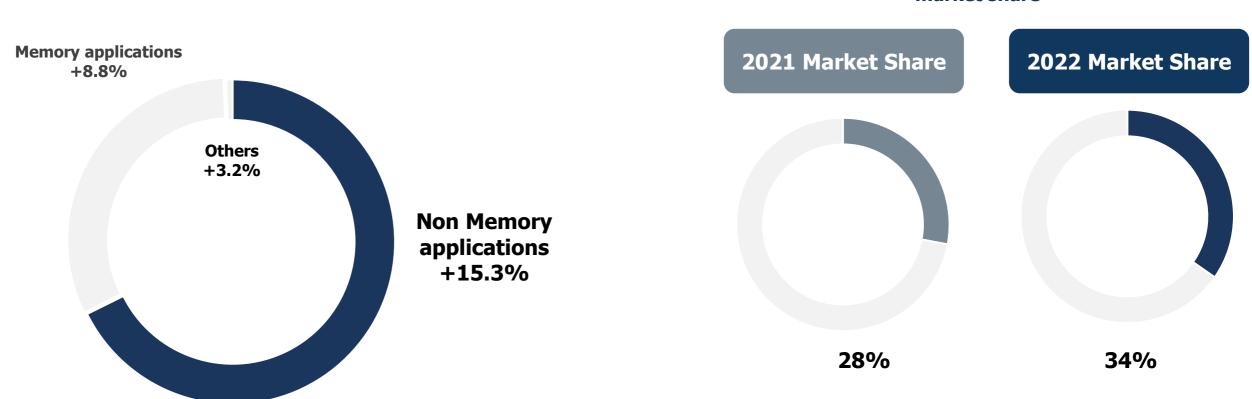
Our serviceable available market

Semiconductor Probe Cards Market 2019-2022 CAGR*

Overall market growth: +12.5%

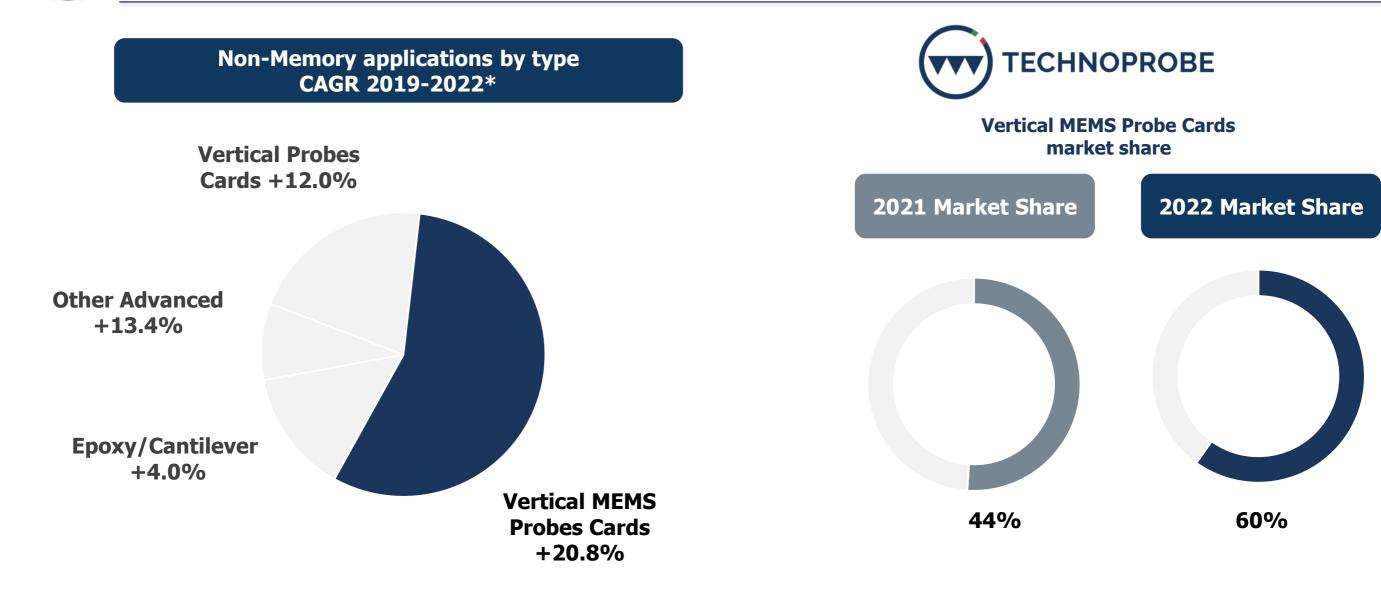


Non-memory applications market share

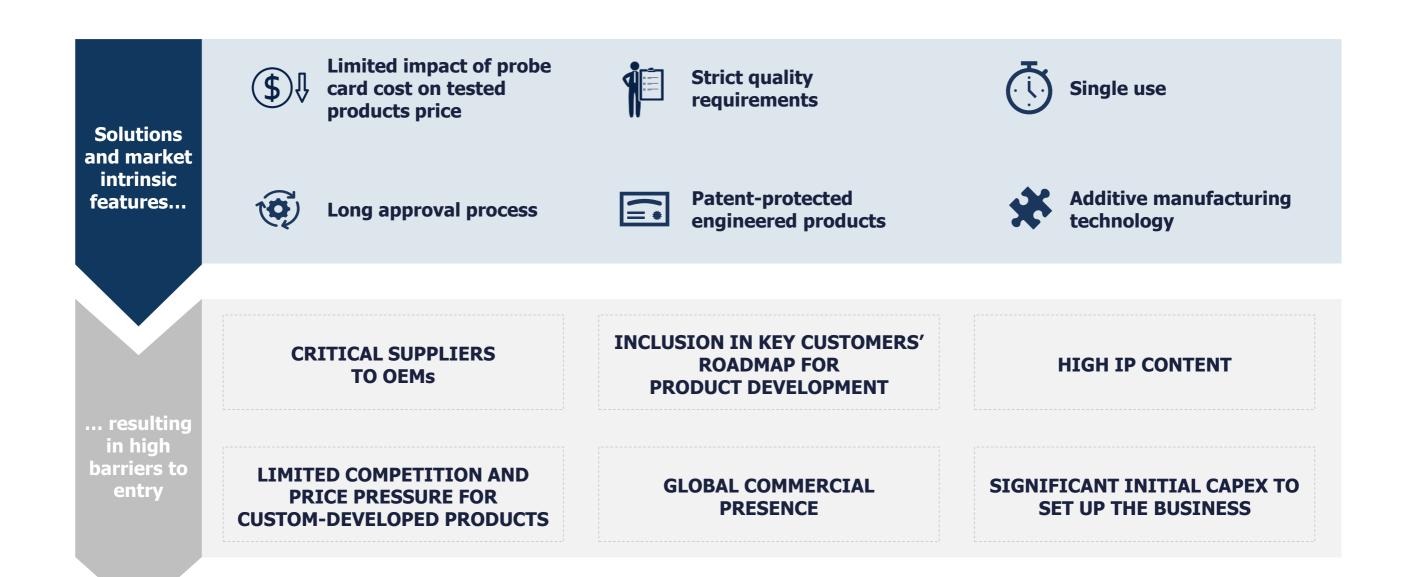




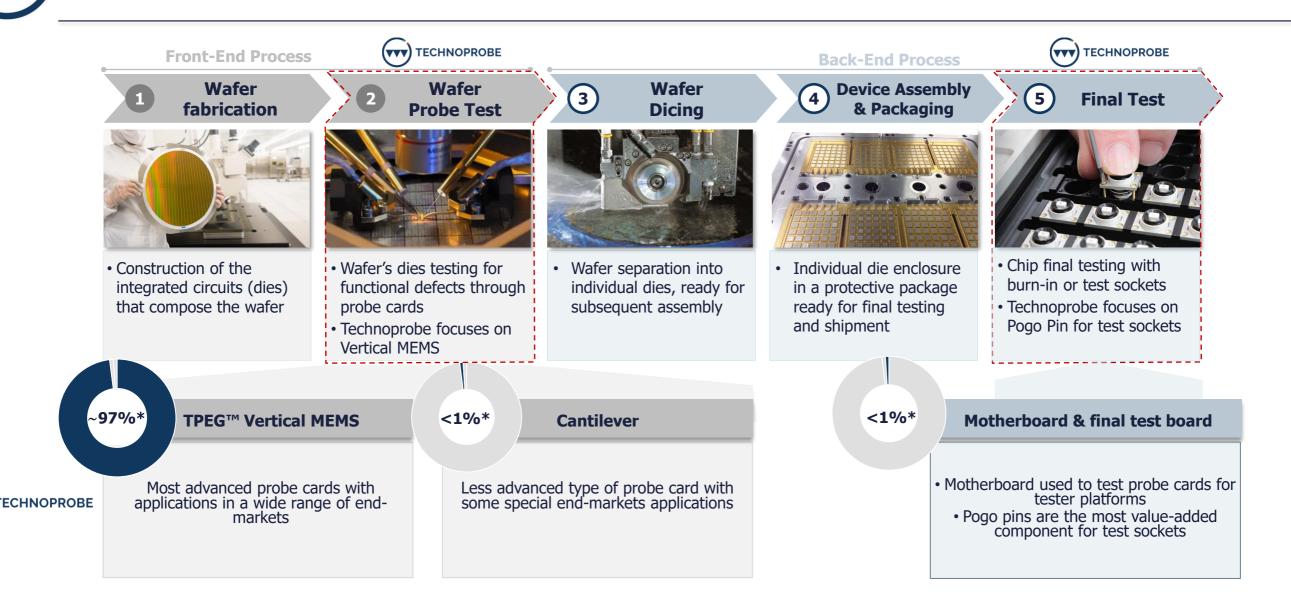
Our serviceable available market



Compelling market characterized by solid entry barriers



Probe cards in the semiconductor manufacturing process



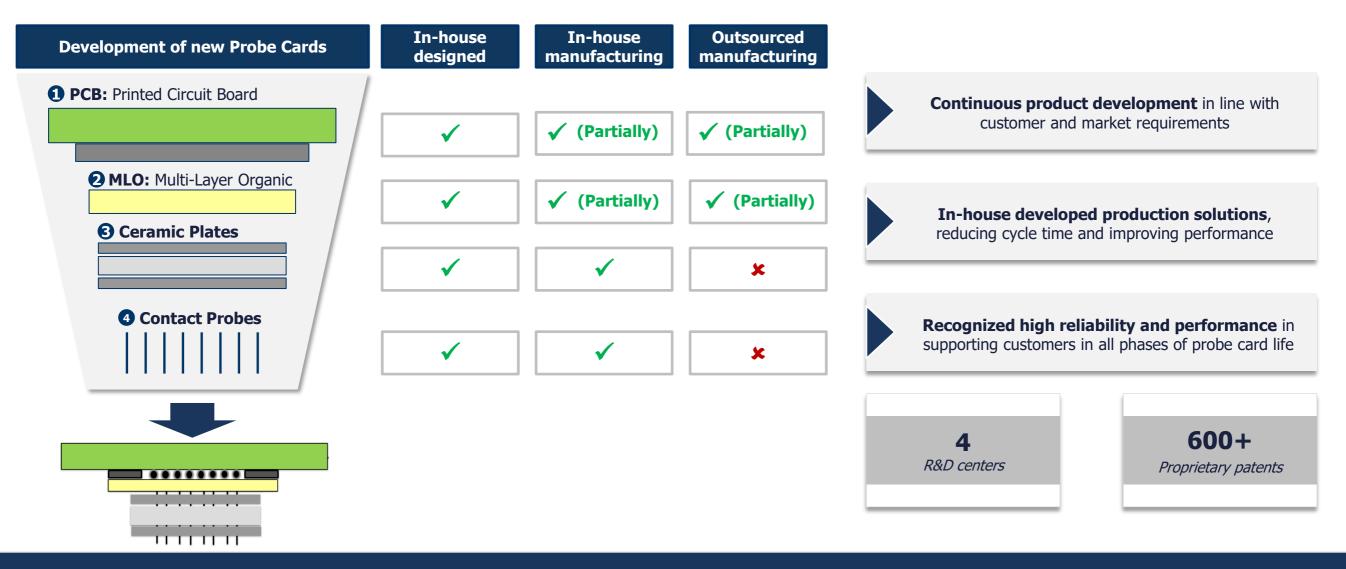


Business Model

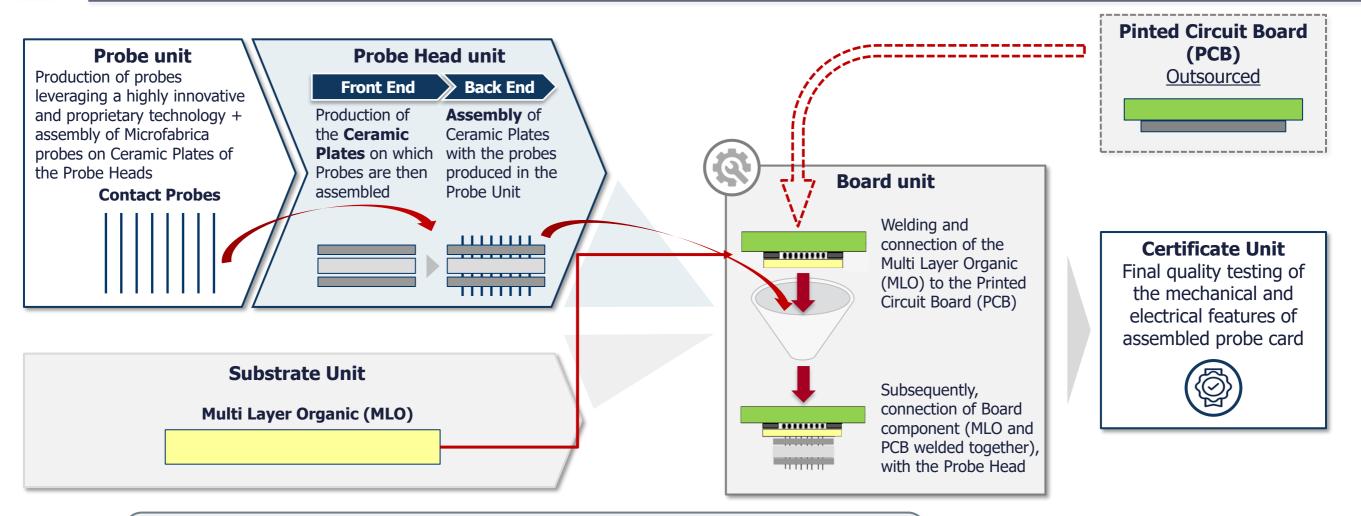


A successful and vertically integrated business model

A winning business model has allowed **Technoprobe** to become the point of reference in the **MEMS non-memory-use market** thanks to the superior quality and performance of its products



Overview of the Probe Cards manufacturing process



Mechanical Shop

- Production of the mechanical elements used across all stages of the probe card manufacturing process
- The unit is also engaged in the production of highly innovative and customized machines, not available on the market, used in the production process

Extensive global presence and widespread local footprint



An extensive range of highly innovative technologies

Advanced Micromachining

Advanced laser cutting: High accuracy and fast lead time

3D MEMS

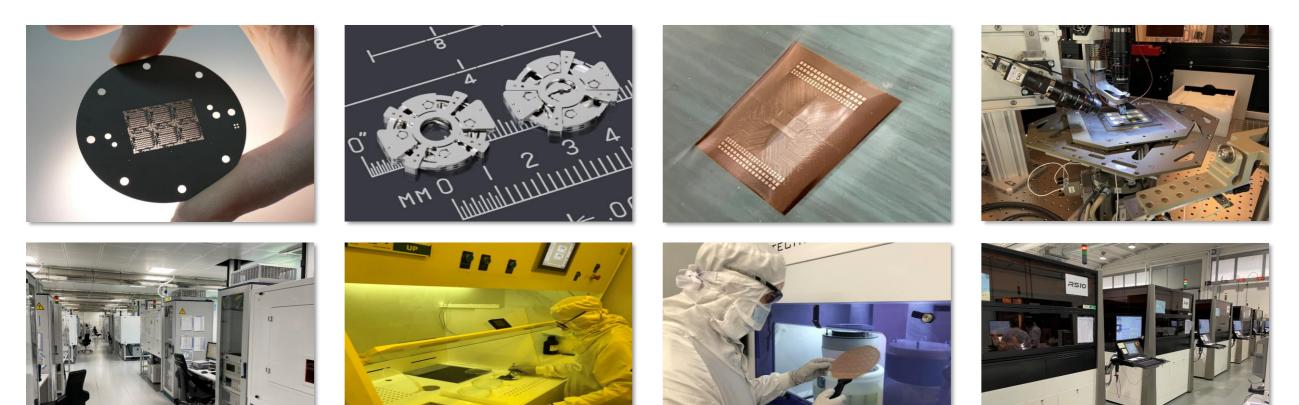
Acquisition of MICROFABRICA in 2019; the sole company in the world specialized in 3D metallic MEMS manufacturing

Thin film

Strong investment in advanced thin film technology to reduce lead time and improve quality and complexity

Advanced manufacturing

Advanced manufacturing for high volume and best quality assembly of micro components



Technoprobe ranked 1st Probe Cards Supplier of 2023

For the sixth year in a row, we are the Highest-Rated Test Subsystems Supplier in the TechInsights Customer Satisfaction Survey*

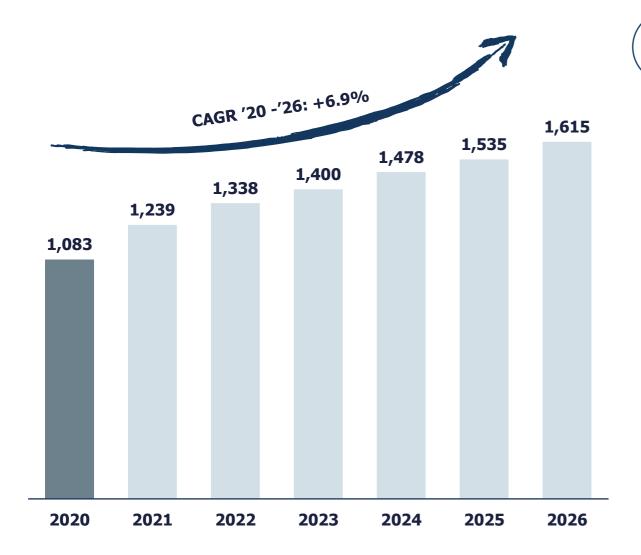




Semiconductor Probe Cards market future estimates

Non-memory Vertical MEMS and vertical probe cards evolution (2020-2026, \$m)*

Digital transformation macro-trends driving market growth



DIGITAL DATA AND 5G: increasing flow of data and ability to access it will drive market growth

DATA CENTER: use of data centers in industrial settings is growing, where sensor technology, robotics and AI in manufacturing are driving demand



MOBILITY AND AUTOMOTIVE: autonomous driving, driver assistance and micro-mobility increase demand for digital solutions and devices

TELCO & MEDIA: speed and accuracy of signal transmission have become fundamental aspects that drive the search for increasingly high performance solutions

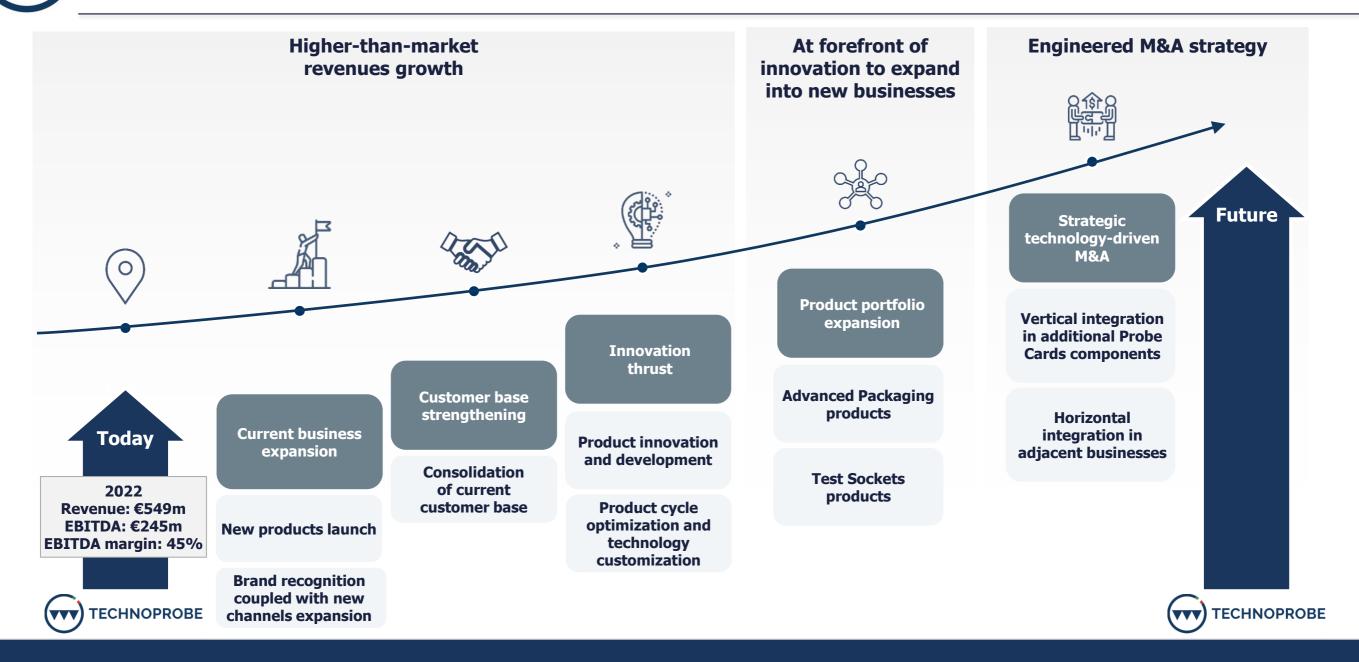


INDUSTRIAL / AEROSPACE: growing demand for sensors related to the adoption of tightly controlled processes associated with quality control requirements, as well as equipment monitoring and maintenance



AUTOMOTIVE SECURITY: ISO26262 functional safety standard requires automated systems to ensure safe cars and the sensitivity and accuracy of digital solutions are the basis for new developments in the automotive sector

Overview of main strategic initiatives

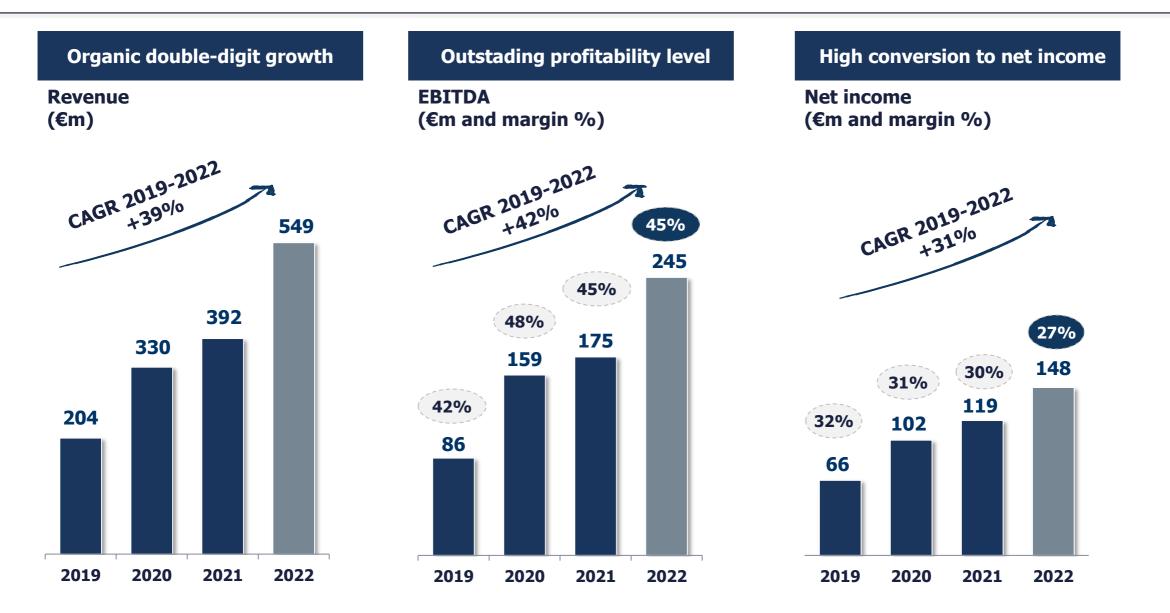




Key Financial Data



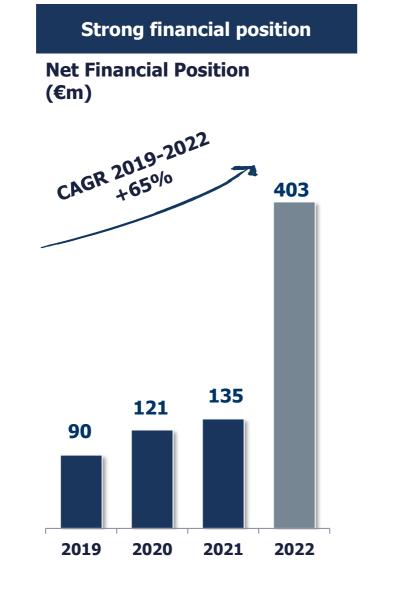
2019 – 2022 Key financial Data



INNOVATION BEGINS WITH US

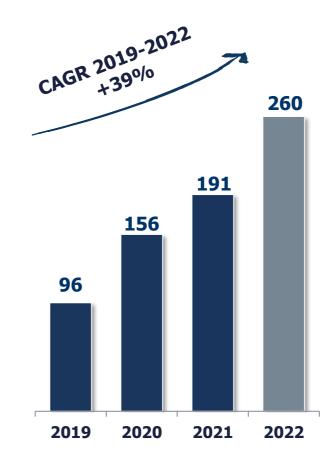
The combined consolidated financial statements as of and for the years ended December 31, 2020 and 2019 represent the combination of (i) the consolidated financial statements of Technoprobe S.p.A. and (ii) the financial information prepared in accordance with IFRS of the following investments transferred through the Demerger: Technoprobe France S.A.S., Technoprobe Korea Co Ltd, Technoprobe Japan KK, Technoprobe Asia Pte Ltd and GeniusPack Holding SA 2019-2020 Combined Consolidated = 2021 Consolidation Perimeter





High Cash Generation

Operating Cash Flow (€m)



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